

FIG.1B

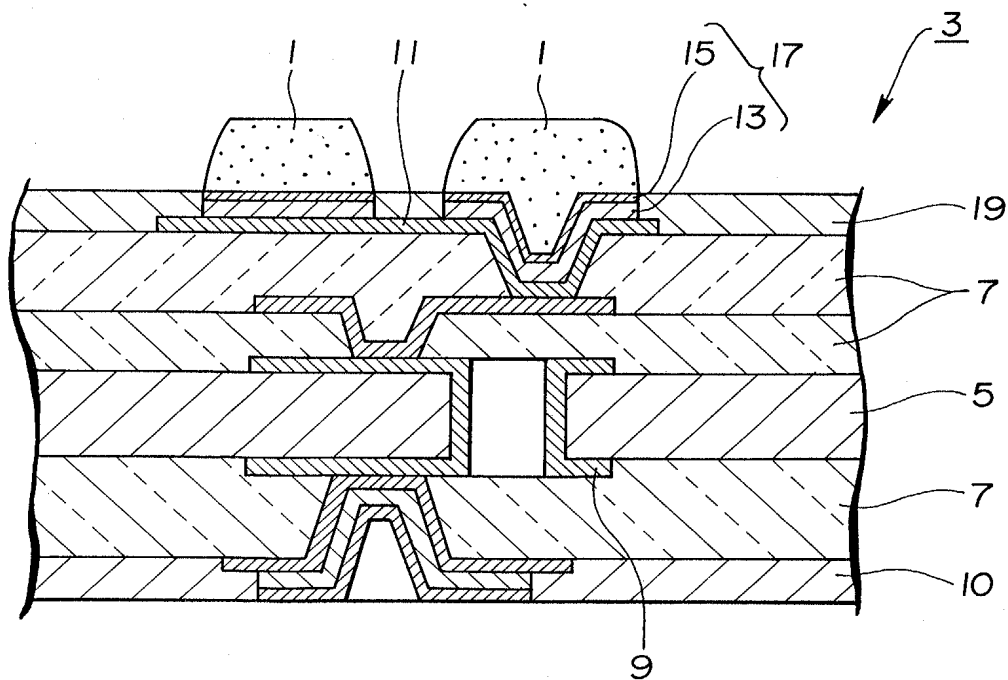
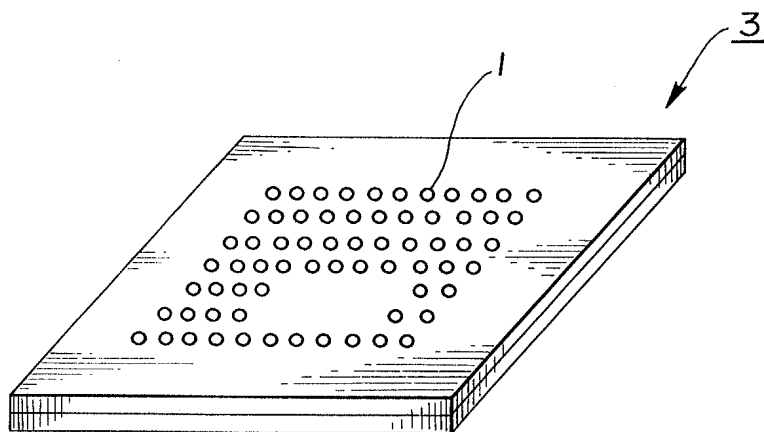




FIG.3

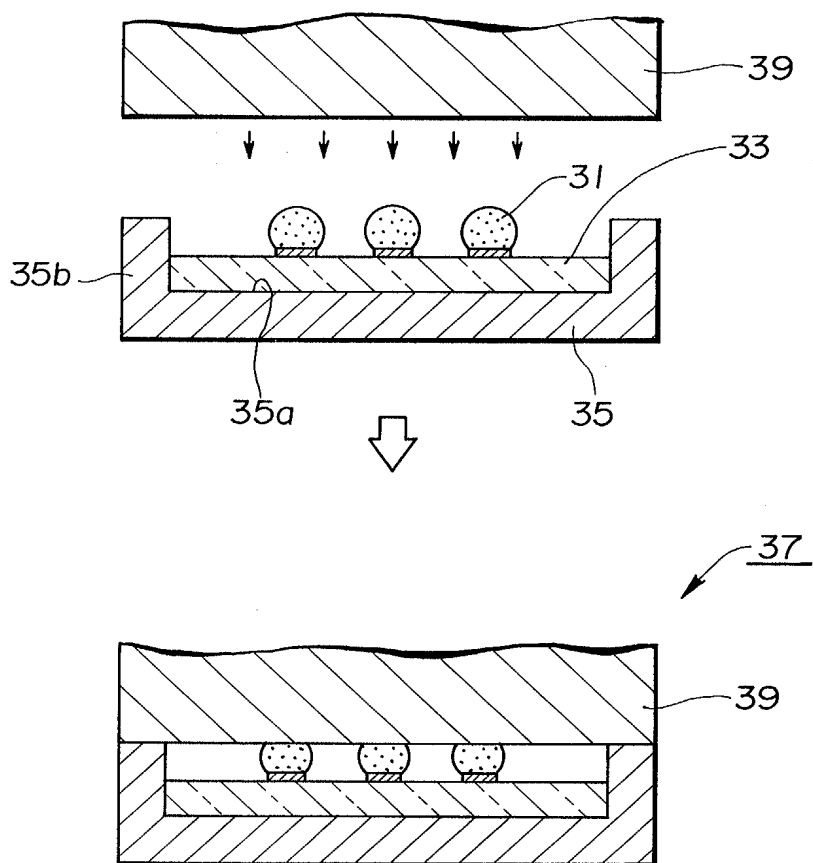


FIG.4A

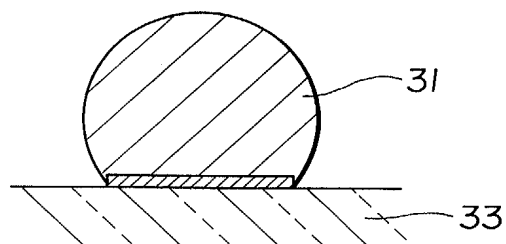


FIG.4B

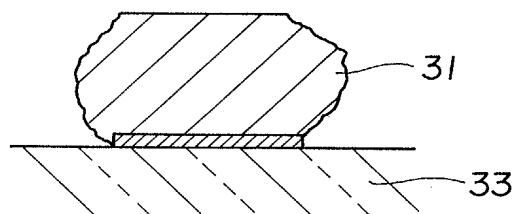


FIG.4C

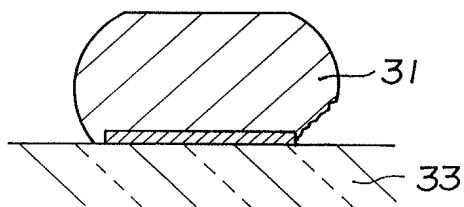


FIG.5

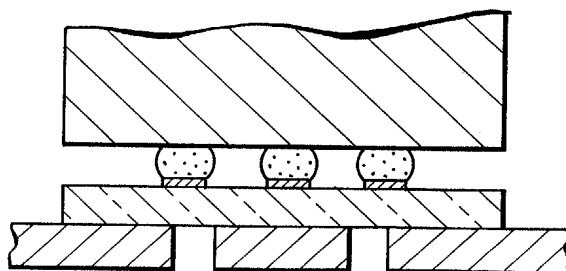
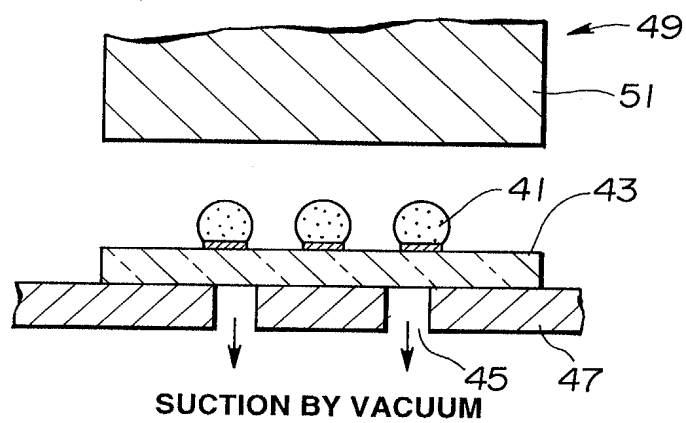


FIG.6

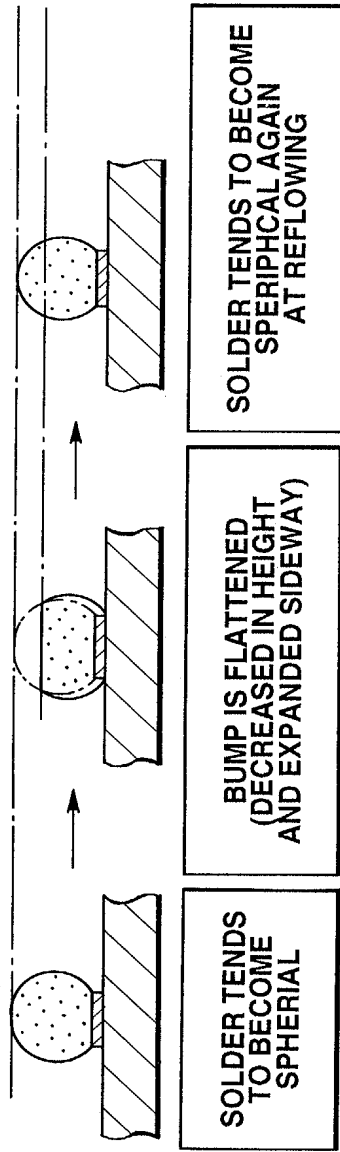


FIG.7

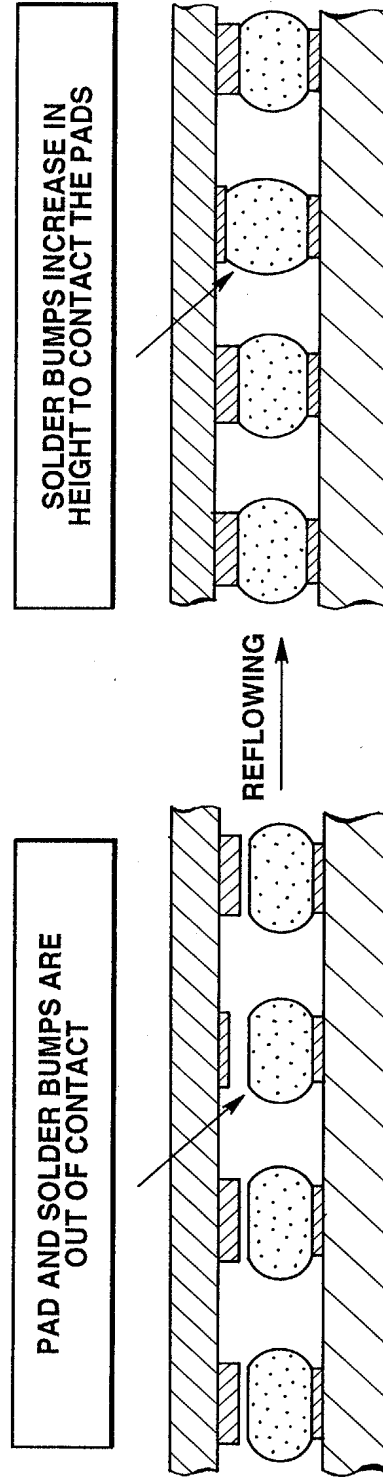
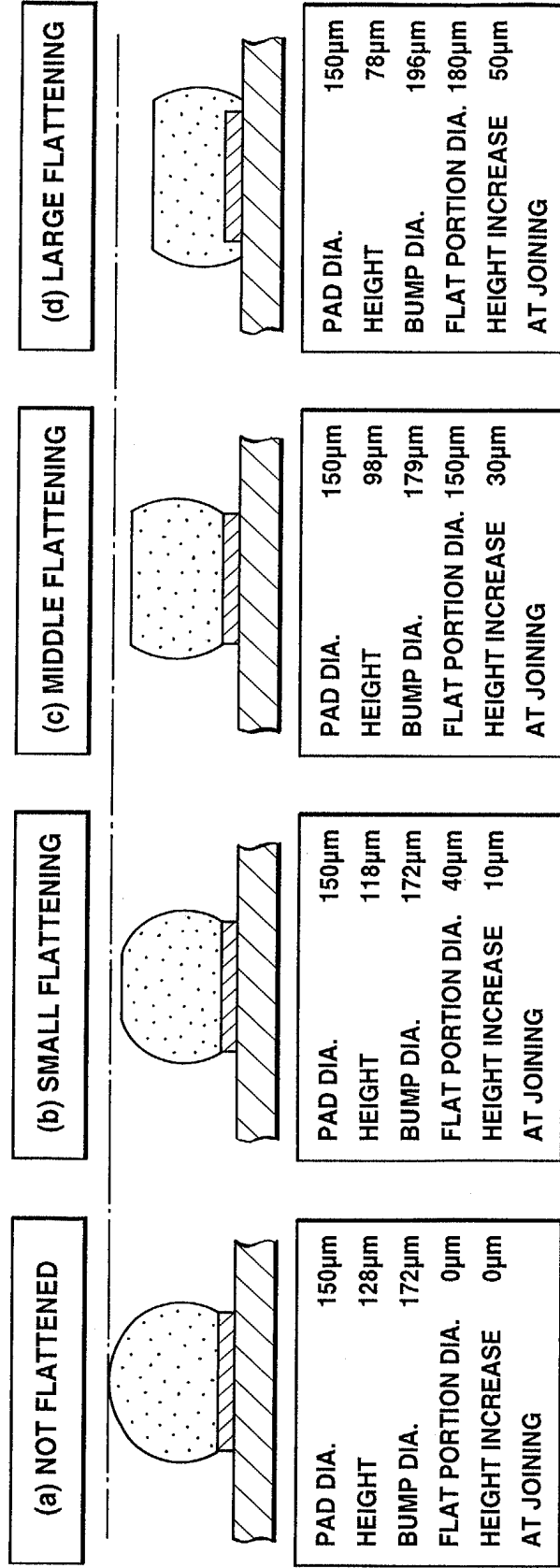


FIG.8



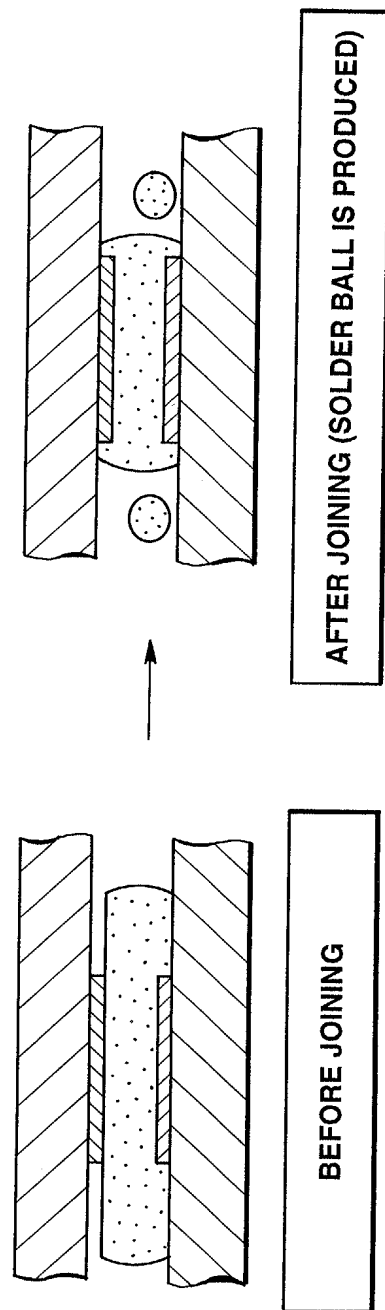


FIG. 10

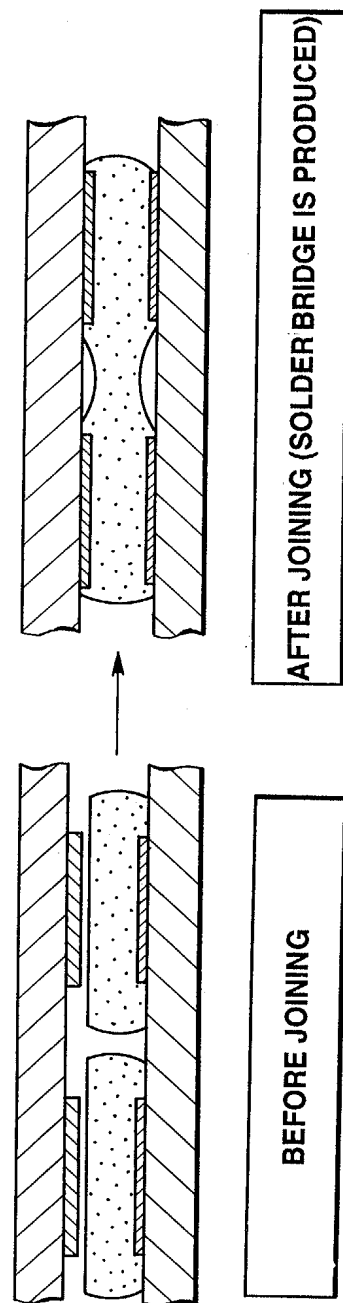


FIG.11A

AT THE TIME OF
FLATTENING
OF SOLDER BUMP

BUMP HEIGHT	T
FLAT PORTION DIA.	$2r$
BUMP DIA.	$2R$
PAD DIA.	$2r$
BUMP VOLUME	S

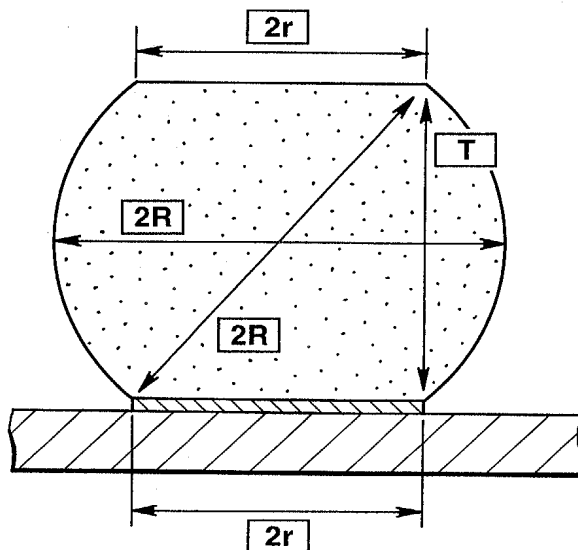


FIG.11B

AT THE TIME OF
REFLOWING
OF SOLDER BUMP

BUMP HEIGHT	$L + t$
BUMP DIA.	$2L$
PAD DIA.	$2r$
BUMP VOLUME	S

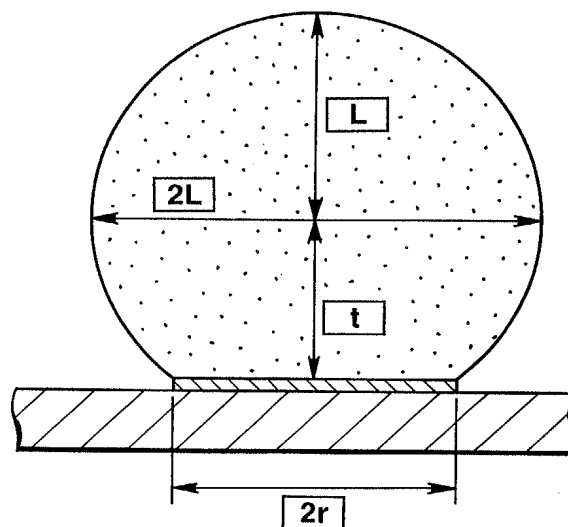


FIG.12A

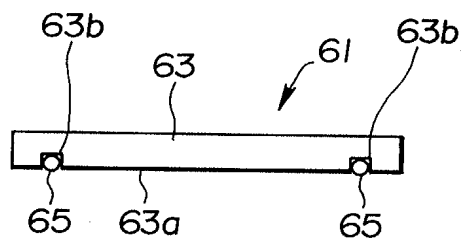


FIG.12C

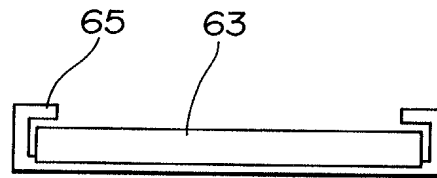


FIG.12B

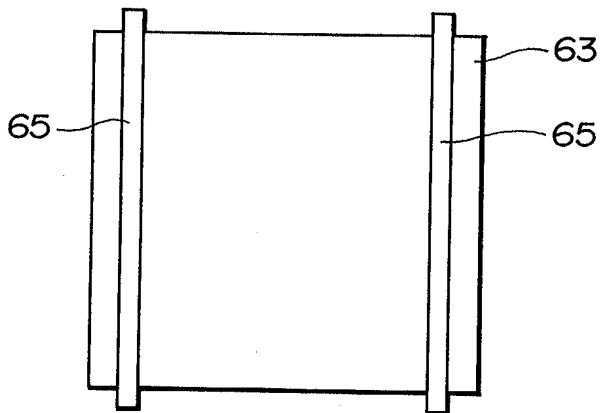


FIG.13A

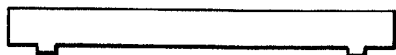


FIG.13C



FIG.13B

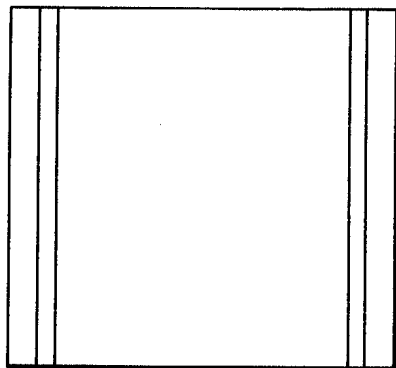


FIG.14A

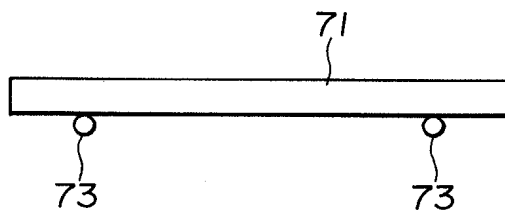


FIG.14B

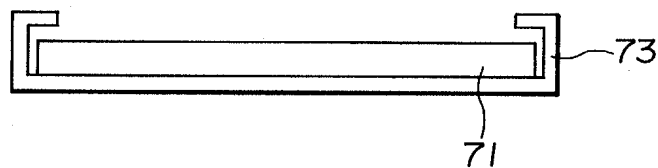


FIG.15A

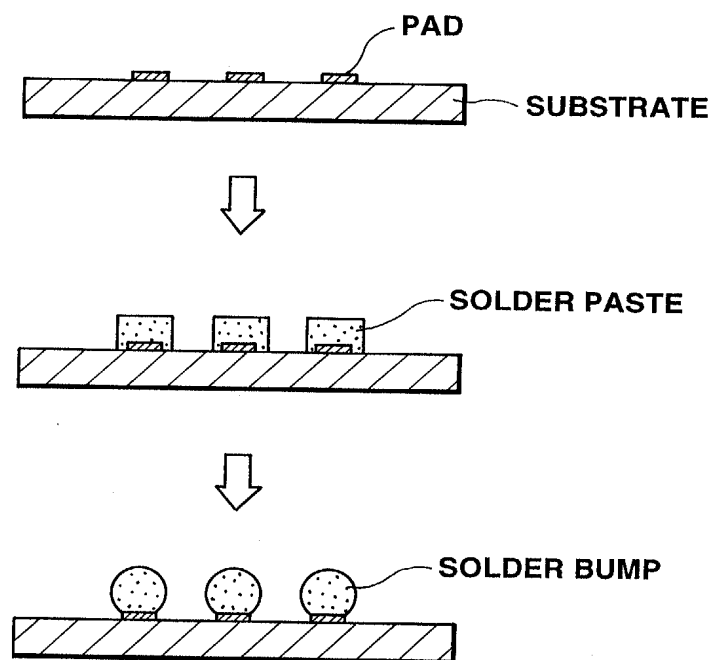


FIG.15B

